

# 1.65 V to 3.6 V, Single-Channel Level Translator in SOT-66 Package

ADG3231

#### **FEATURES**

Operates from 1.65 V to 3.6 V supply rails
Unidirectional signal path
Up/down level translation
Ultracompact 6-lead SOT-66 and SOT-23 packages
Output short-circuit protection
LVTTL-/CMOS-compatible inputs

## **APPLICATIONS**

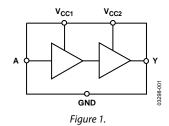
Level translation in PDAs Handsets MP3 players

## **GENERAL DESCRIPTION**

The ADG3231 is a single-channel level translator designed on a submicron process that is guaranteed to operate over the 1.65 V to 3.6 V supply range. The device can be used in applications requiring communication between digital devices operating from multiple supply voltages. The logic levels on each side of the device are set by the two supply voltages,  $V_{\text{CC1}}$  for A and  $V_{\text{CC2}}$  for Y. The signal path is unidirectional, meaning data can flow only from A to Y.

The ADG3231 can operate with any combination of  $V_{\rm CC1}$  and  $V_{\rm CC2}$  supply voltages within the 1.65 V to 3.6 V range, allowing the part to perform either up ( $V_{\rm CC1} < V_{\rm CC2}$ ) or down ( $V_{\rm CC1} > V_{\rm CC2}$ ) level translation. The output stage is protected against current overload, which can occur when the Y pin is accidentally shorted to the  $V_{\rm CC2}$  or GND rails.

#### **FUNCTIONAL BLOCK DIAGRAM**



The ADG3231 is available in ultracompact packages, the SOT-66 (1.65 mm  $\times$  1.66 mm  $\times$  0.57 mm) and the SOT-23 (2.8 mm  $\times$  2.9 mm  $\times$  1.3 mm), making the part ideal for applications where space is critical.

### **PRODUCT HIGHLIGHTS**

- 1. Up/down level translation.
- 2. Guaranteed to operate with any supply combination within the 1.65 V to 3.6 V range.
- 3. Output short-circuit protection.
- 4. Available in ultracompact SOT-66 and SOT-23 packages.

# **TABLE OF CONTENTS**

Changes to Features, Applications, General Description and Product Highlights Sections	5/03—Revision 0: Initial Version
Change to Data Sheet Title	Changes to Ordering Guide
Added SOT-66 PackageUniversal	Updated Outline Dimensions
Updated Format	Changes to Theory of Operation Section9
12/04—Rev. 0 to Rev. A	Changes to Figure 13 through Figure 20
Changes to Ordering Guide	Deleted TPC 1 to TPC 6
Deleted Figure 11 and Figure 12	Changes to Figure 2 and Figure 3
5/06—Rev. A to Rev. B	Changes to Figure 1
REVISION HISTORY	Changes to Figure 1
Specifications	Ordering Guide
Revision History	Outline Dimensions
Product Highlights	Theory of Operation9
General Description	Typical Performance Characteristics6
Functional Block Diagram	Pin Configurations and Function Descriptions5
Applications	ESD Caution4
Features1	Absolute Maximum Ratings4

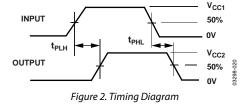
# **SPECIFICATIONS**

 $V_{\text{CC1}} = V_{\text{CC2}} = 1.65 \text{ V}$  to 3.6 V, GND = 0 V. All specifications  $T_{\text{MIN}}$  to  $T_{\text{MAX}}$ , unless otherwise noted. Temperature range for the B version is -40°C to +85°C.

Table 1.

Parameter	Symbol	Conditions	Min	Typ <sup>1</sup>	Max	Unit
LOGIC INPUTS/OUTPUTS				•		
Input High Voltage <sup>2</sup>	V <sub>IH</sub>	$V_{CC1} = 3.0 \text{ V to } 3.6 \text{ V}$	1.35			V
		$V_{CC1} = 2.3 \text{ V to } 2.7 \text{ V}$	1.35			V
		$V_{CC1} = 1.65 \text{ V to } 1.95 \text{ V}$	0.65 V <sub>CC1</sub>			V
Input Low Voltage <sup>2</sup>	$V_{IL}$	$V_{CC1} = 3.0 \text{ V to } 3.6 \text{ V}$			0.8	V
		$V_{CC1} = 2.3 \text{ V to } 2.7 \text{ V}$			0.7	V
		$V_{CC1} = 1.65 \text{ V to } 1.95 \text{ V}$			$0.35V_{\text{CC1}}$	V
Output High Voltage	V <sub>OH</sub>	$I_{OH} = -100 \mu A$ , $V_{CC2} = 3.0 \text{ V to } 3.6 \text{ V}$	2.4			V
		$I_{OH} = -100 \mu A$ , $V_{CC2} = 2.3 V$ to 2.7 V	2.0			V
		$I_{OH} = -100 \mu A$ , $V_{CC2} = 1.65 \text{ V to } 1.95 \text{ V}$	V <sub>CC2</sub> - 0.45			V
		$I_{OH} = -4 \text{ mA}, V_{CC2} = 2.3 \text{ V to } 2.7 \text{ V}$	2.0			٧
		$I_{OH} = -4 \text{ mA}, V_{CC2} = 1.65 \text{ V to } 1.95 \text{ V}$	V <sub>CC2</sub> - 0.45			٧
		$I_{OH} = -8 \text{ mA}, V_{CC2} = 3.0 \text{ V to } 3.6 \text{ V}$	2.4			V
Output Low Voltage	V <sub>OL</sub>	$I_{OL} = 100 \mu\text{A}, V_{CC2} = 3.0 \text{V} \text{ to } 3.6 \text{V}$			0.4	V
		$I_{OL} = 100  \mu A$ , $V_{CC2} = 2.3  V$ to 2.7 V			0.4	٧
		$I_{OL} = 100 \mu A$ , $V_{CC2} = 1.65 V$ to 1.95 V			0.45	٧
		$I_{OL} = 4 \text{ mA}, V_{CC2} = 2.3 \text{ V to } 2.7 \text{ V}$			0.4	V
		$I_{OL} = 4 \text{ mA}, V_{CC2} = 1.65 \text{ V to } 1.95 \text{ V}$			0.45	٧
		$I_{OL} = 8 \text{ mA}, V_{CC2} = 3.0 \text{ V to } 3.6 \text{ V}$			0.4	V
SWITCHING CHARACTERISTICS <sup>2</sup>						
Propagation Delay, t <sub>PD</sub> A to Y	t <sub>PHL</sub> , t <sub>PLH</sub>	$3.3 \text{ V} \pm 0.3 \text{ V}$ , $C_L = 30 \text{ pF}$ , see Figure 2		4	6.5	ns
Propagation Delay, t <sub>PD</sub> A to Y	t <sub>PHL</sub> , t <sub>PLH</sub>	$2.5 \text{ V} \pm 0.2 \text{ V}$ , $C_L = 30 \text{ pF}$ , see Figure 2		4.5	6.5	ns
Propagation Delay, t <sub>PD</sub> A to Y	t <sub>PHL</sub> , t <sub>PLH</sub>	$1.8 \text{ V} \pm 0.15 \text{ V}$ , $C_L = 30 \text{ pF}$ , see Figure 2		6.5	10.25	ns
Input Leakage Current	l <sub>l</sub>	$0 \le V_{IN} \le 3.6 V$			±1	μΑ
Output Leakage Current	lo	$0 \le V_{IN} \le 3.6 V$			±1	μΑ
POWER REQUIREMENTS						
Power Supply Voltages	$V_{CC1}$		1.65		3.6	٧
	V <sub>CC2</sub>		1.65		3.6	V
<b>Quiescent Power Supply Current</b>	I <sub>CC1</sub>	Digital inputs = 0 V or V <sub>CC1</sub>			2	μΑ
	I <sub>CC2</sub>	Digital inputs = 0 V or V <sub>CC2</sub>			2	μΑ

 $<sup>^1</sup>$  All typical values are at V  $_{CC1}$  = V  $_{CC2}$  , T  $_A$  = 25  $^{\circ}$  C, unless otherwise noted.  $^2$  Guaranteed by design, not subject to production test.



## **ABSOLUTE MAXIMUM RATINGS**

 $T_A = 25$ °C, unless otherwise noted.

Table 2.

Parameter	Rating
V <sub>CC</sub> to GND	-0.3 V to +4.6 V
Input Voltage for A	$-0.3 \text{ V to V}_{CC1} + 0.3 \text{ V}$
DC Output Current	25 mA
Operating Temperature Range	
Industrial (B Version)	−40°C to +85°C
Storage Temperature Range	−65°C to +150°C
Junction Temperature	150°C
$\theta_{JA}$ Thermal Impedance	
6-Lead SOT-23	229°C/W
6-Lead SOT-66	191°C/W (4-layer board)
Lead Temperature, Soldering (10 sec)	300°C
IR Reflow, Peak Temperature (<20 sec)	235°C

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

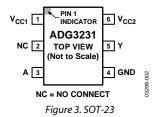
Only one absolute maximum rating may be applied at any one time.

## **ESD CAUTION**

ESD (electrostatic discharge) sensitive device. Electrostatic charges as high as 4000 V readily accumulate on the human body and test equipment and can discharge without detection. Although this product features proprietary ESD protection circuitry, permanent damage may occur on devices subjected to high energy electrostatic discharges. Therefore, proper ESD precautions are recommended to avoid performance degradation or loss of functionality.



# PIN CONFIGURATIONS AND FUNCTION DESCRIPTIONS



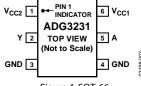


Figure 4. SOT-66

**Table 3. Pin Function Descriptions** 

Pin	Number			
SOT-23	SOT-66	Mnemonic	Description	
1	6	V <sub>CC1</sub>	Supply Voltage 1. Can be any supply voltage from 1.65 V to 3.6 V.	
2	_	NC	Not internally connected.	
3	5	Α	Digital Input Referred to V <sub>CC1</sub> .	
4	3, 4	GND	Device Ground Pin.	
5	2	Υ	Digital Output Referred to V <sub>CC2</sub> .	
6	1	V <sub>CC2</sub>	Supply Voltage 2. Can be any supply voltage from 1.65 V to 3.6 V.	

## TYPICAL PERFORMANCE CHARACTERISTICS

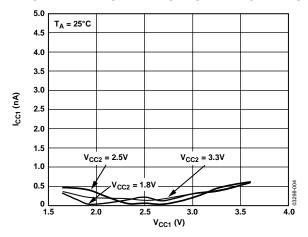


Figure 5. Icc1 vs. Vcc1

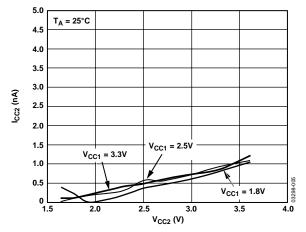


Figure 6. I<sub>CC2</sub> vs. V<sub>CC2</sub>

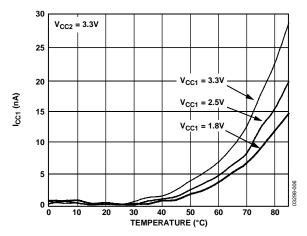


Figure 7. I<sub>CC1</sub> vs. Temperature

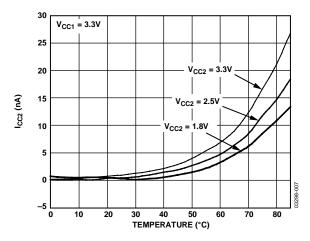


Figure 8. Icc2 vs. Temperature

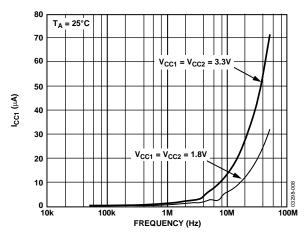


Figure 9. I<sub>CC1</sub> vs. Frequency

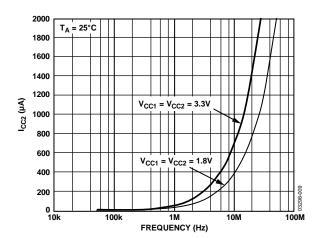


Figure 10. Icc2 vs. Frequency

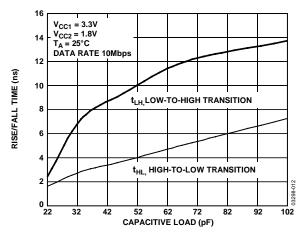


Figure 11. Rise/Fall Time vs. Capacitive Load (3.3 V to 1.8 V Level Translation)

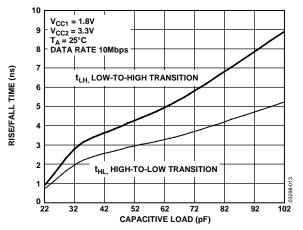


Figure 12. Rise/Fall Time vs. Capacitive Load (1.8 V to 3.3 V Level Translation)

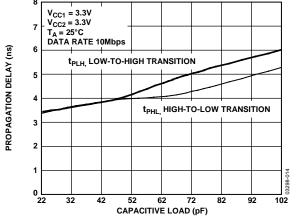


Figure 13. Propagation Delay vs. Capacitive Load

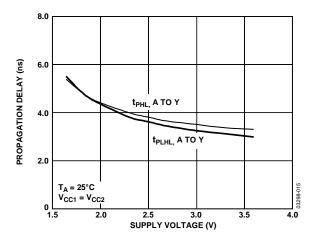


Figure 14. Propagation Delay vs. Supply Voltage

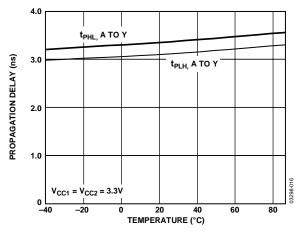


Figure 15. Propagation Delay vs. Temperature

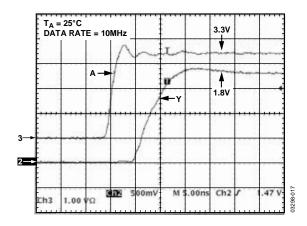


Figure 16. Input/Output  $V_{CC1} = 3.3 \text{ V}$ ,  $V_{CC2} = 1.8 \text{ V}$ 

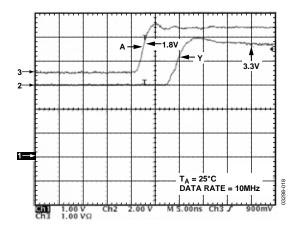


Figure 17. Input/Output  $V_{CC1} = 1.8 \text{ V}$ ,  $V_{CC2} = 3.3 \text{ V}$ 

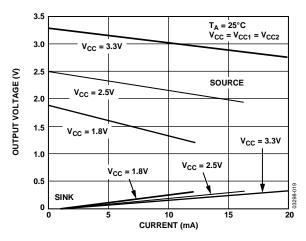


Figure 18. Output Voltage vs. Sink and Source Current

## THEORY OF OPERATION

The ADG3231 is a single-channel level translator designed on a submicron process that is guaranteed to operate over the 1.65 V to 3.6 V supply range. The device can be used in applications requiring communication between digital devices operating from multiple supply voltages. The logic levels on each side of the device are set by the two supply voltages,  $V_{\rm CC1}$  for A, and  $V_{\rm CC2}$  for Y. The signal path is unidirectional, meaning data can flow only from A to Y.

The ADG3231 can operate with any combination of  $V_{\rm CC1}$  and  $V_{\rm CC2}$  supply voltages within the 1.65 V to 3.6 V range, allowing the part to perform either up ( $V_{\rm CC1}$  <  $V_{\rm CC2}$ ) or down ( $V_{\rm CC1}$  >  $V_{\rm CC2}$ ) level translation.

By limiting the current delivered into the load, for example,  $\sim 1.7$  mA with  $V_{\rm CC2} = 3.6$  V, the output stage is protected against current overload, which can occur when the Y pin is accidentally shorted to the  $V_{\rm CC2}$  or GND rails.

The short-circuit protection circuitry works by limiting the output current when the output voltage exceeds  $V_{\rm OL}~(A=0~logic)$  or is less than  $V_{\rm OH}~(A=1~logic)$  threshold values specified for the  $V_{\rm CC2}$  supply voltage used.

Figure 19 shows a typical application for the ADG3231 where the device performs level translation from  $V_{\rm CC1}\text{-compatible}$  levels to  $V_{\rm CC2}\text{-compatible}$  levels to allow proper communication between the two digital devices, DEVICE 1 and DEVICE 2.

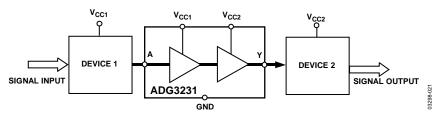
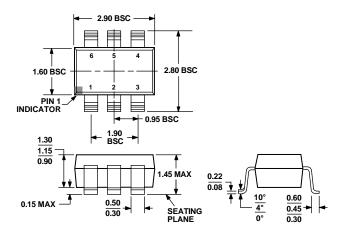


Figure 19. Typical Application of the ADG3231 Level Translator

## **OUTLINE DIMENSIONS**



COMPLIANT TO JEDEC STANDARDS MO-178-AB

Figure 20. 6-Lead Small Outline Transistor Package [SOT-23] (RJ-6) Dimensions shown in millimeters

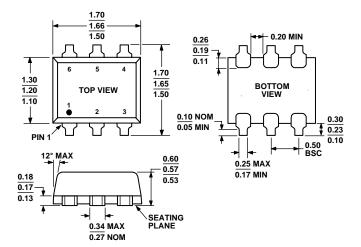


Figure 21. 6-Lead Small Outline Transistor Package [SOT-66] (RY-6-1) Dimensions shown in millimeters

## **ORDERING GUIDE**

ONDERING GOIDE						
Model	Temperature Range	Package Description	Package Option	Branding		
ADG3231BRJ-REEL	−40°C to +85°C	6-Lead SOT-23	RJ-6	W2B		
ADG3231BRJ-REEL7	-40°C to +85°C	6-Lead SOT-23	RJ-6	W2B		
ADG3231BRJZ-REEL <sup>1</sup>	−40°C to +85°C	6-Lead SOT-23	RJ-6	W2B #		
ADG3231BRJZ-REEL7 <sup>1</sup>	−40°C to +85°C	6-Lead SOT-23	RJ-6	W2B#		
ADG3231BRYZ-REEL7 <sup>1</sup>	-40°C to +85°C	6-Lead SOT-66	RY-6-1	01X <sup>2</sup>		

 $<sup>^{1}</sup>$  Z = Pb-free part, # denotes lead-free may be top or bottom marked.

<sup>&</sup>lt;sup>2</sup> X= date code.

# NOTES

ADG3231			
---------	--	--	--

# NOTES